

ABSTRACT

A cleaning method for a processing chamber and a semiconductor processing device are provided. The method comprises: cleaning the processing chamber using plasma; acquiring opening size information of a flow control valve of an exhaust assembly configured for evacuating the processing chamber; and stopping the cleaning when the opening size information meets a preset condition. In the present disclosure, the endpoint of the cleaning process for the processing chamber can be determined accurately and in real time. Once the cleaning process reaches its endpoint, the cleaning operation is stopped, thereby avoiding both insufficient cleaning and over-cleaning of the processing chamber.